

# LIGHT EMITTING DIODE SPECIFICATION

CUSTOMER NAME:

DESCRIPTION: IE-5RG9GW-C

REVISION : V2.2

ISSUE DATE : 2023-04-28

Contains trade secret information and shall not be made available to, or copied or used by anyone without written permission from the manufacturer. All rights reserved.

**Features:**

- Long operating life
- Low Power Consumption
- Low voltage DC operated
- RoHS Compliant

**Application:**

- Status indicator
- Industrial control panel
- Sensor status indication
- Wearable and portable devices

Part Number	Dice Material	Emitted Color	Lens Color
IE-5RG9GW-C	AlGaInP-AlGaInP	Red-Yellow Green	White Diffused

**Electro-Optical Characteristics** ( $T_a=25^{\circ}\text{C}$ , @20mA)

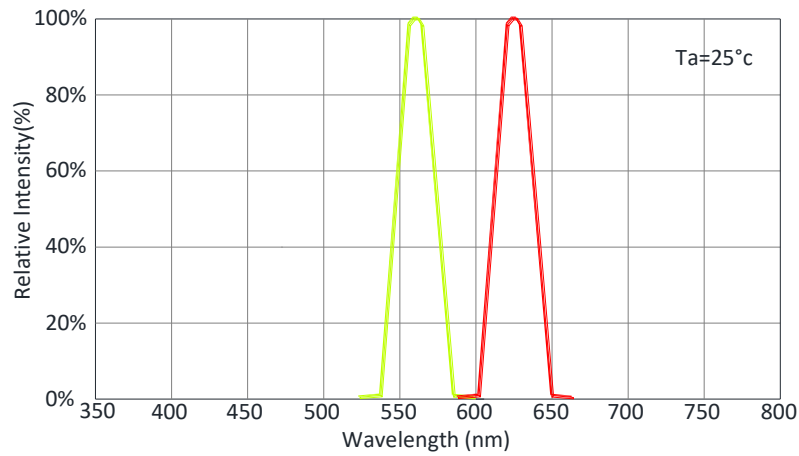
Parameter	Color	Symbol	Min.	Typ.	Max.	Unit
Luminous Intensity	■	IV	100	-	350	mcd
	■		15	-	30	
Radiation Bandwidth	■	$\Delta\lambda$	-	20	-	nm
	■		-	35	-	
Forward Voltage	■	VF	1.90	2.00	2.40	v
	■		1.90	2.00	2.40	
Dominant Wavelength	■	$\lambda_d$	620	625	635	nm
	■		568	570	575	
Viewing Angle	■	2 $\theta$ 1/2	-	60	-	deg
	■		-	60	-	
Reverse Current	-	IR	-	-	10	uA

**Absolute Maximum Ratings** ( $T_a=25^{\circ}\text{C}$ )

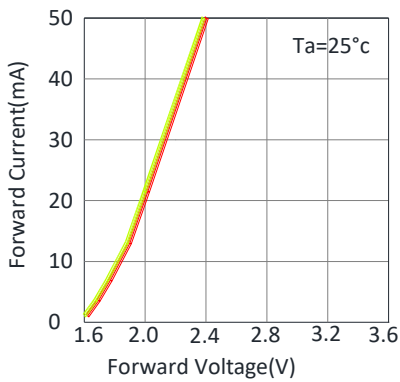
Parameter	Symbol	Max.	Unit
Peak Forward Current(1/10 Duty Cycle, 0.1ms Pulse Width)	IPF	100	mA
Forward Current	IF	30	mA
Reverse Voltage	VR	5	v
Electrostatic Discharge	ESD	2000	v
Operating Temperature Range	Topr	-40to+90	$^{\circ}\text{C}$
Storage Temperature Range	Tstg	-40to+90	$^{\circ}\text{C}$
Reflow Soldering	Tsld	260 $^{\circ}\text{C}$ for 10secs	

### Optical & Electrical Characteristics

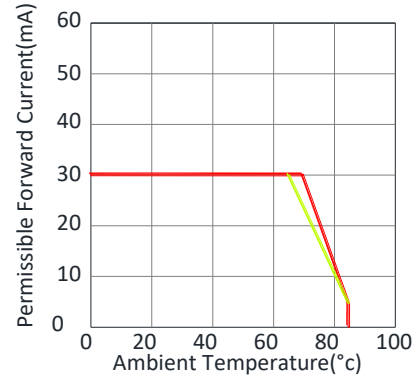
Relative Intensity vs.Wavelength



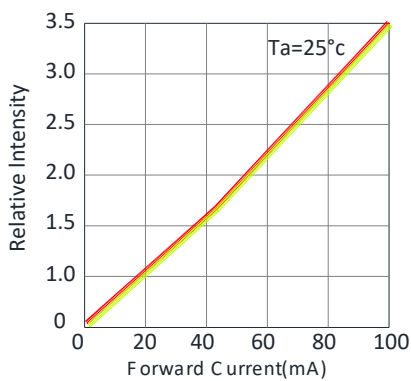
Forward Current vs.Forward Voltage



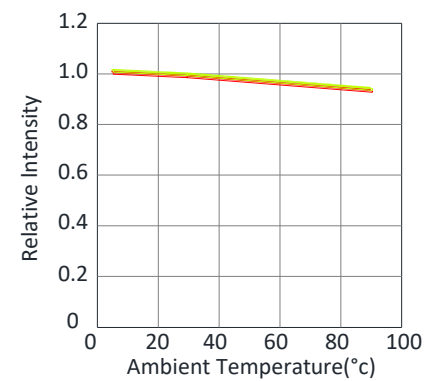
Forward Current vs.Ambient Temperature



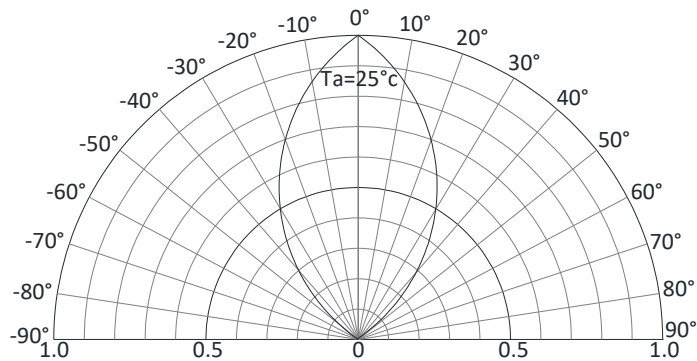
Relative Intensity vs.Forward Current



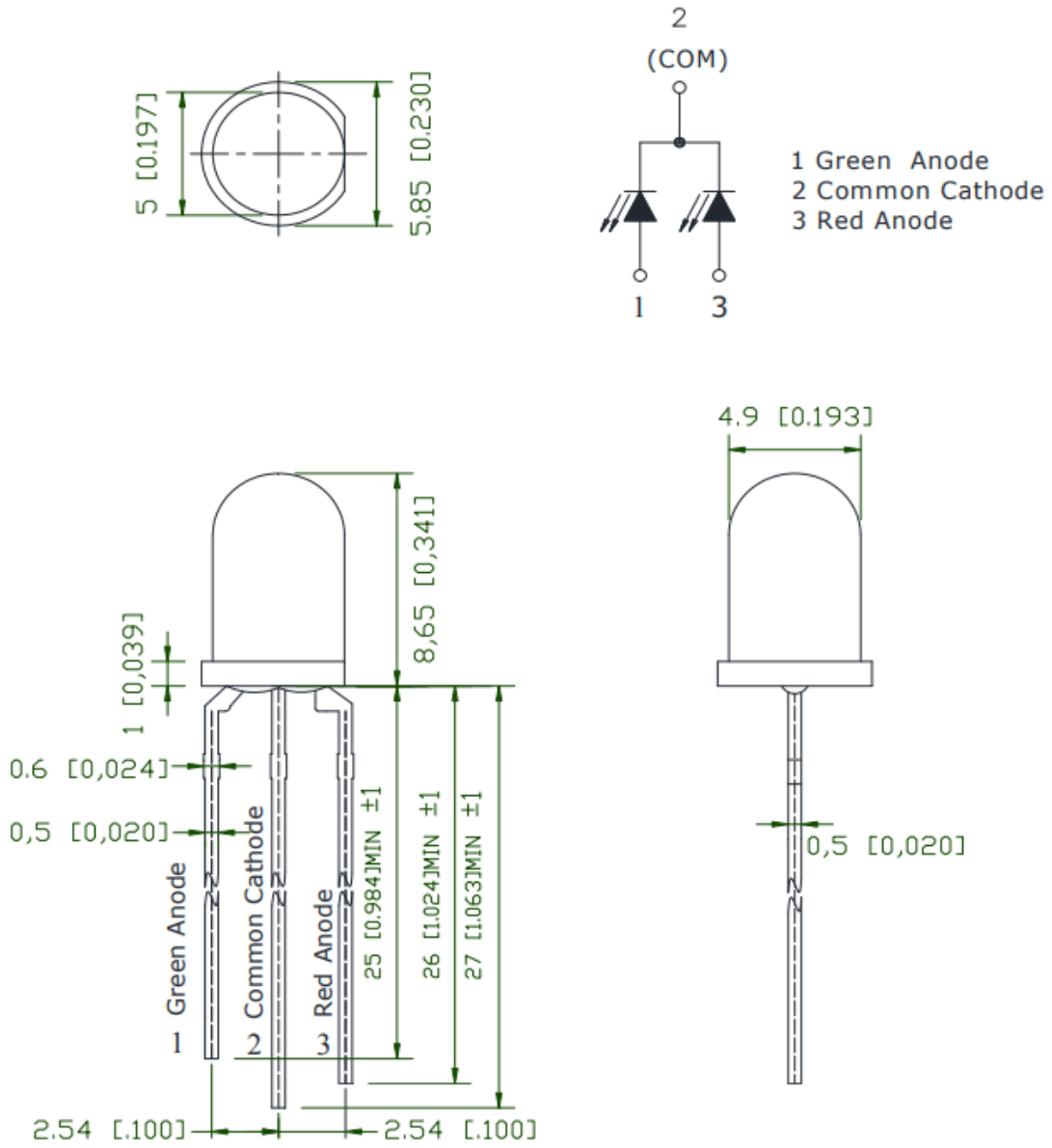
Relative Intensity vs.Ambient Temperature



Radiation Pattern



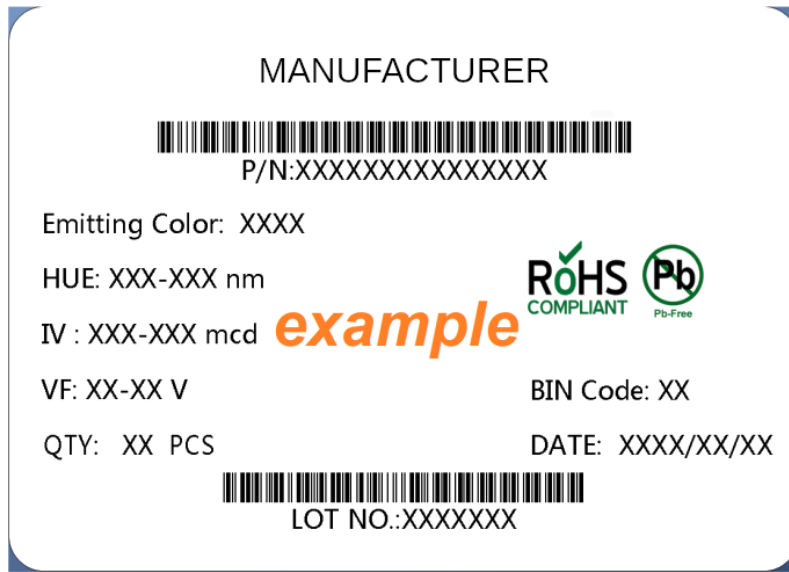
Product size (Unit:mm)



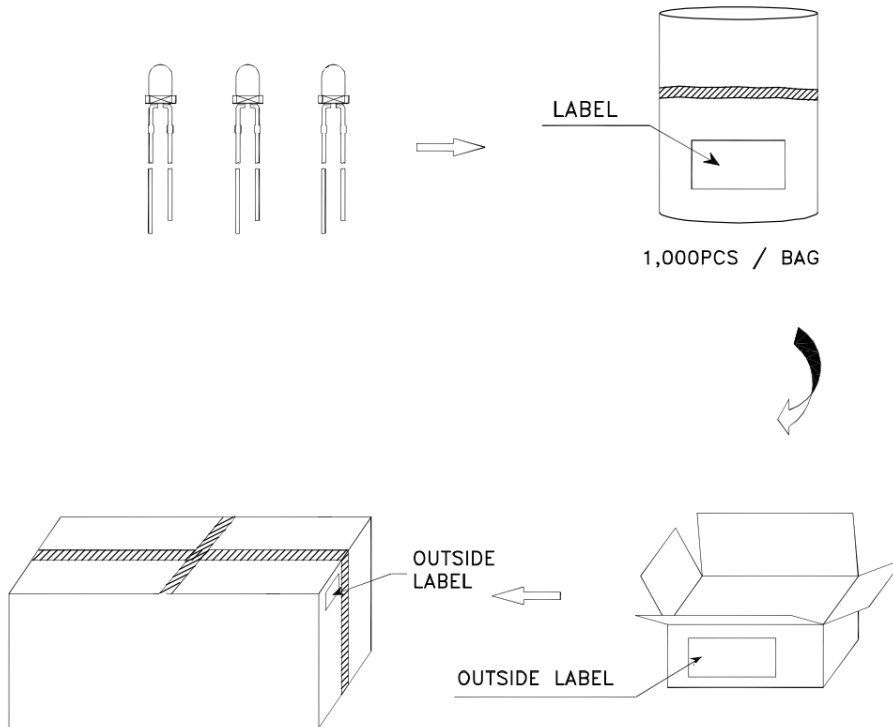
Notes:

1. All dimensions are in millimeters (inches).
2. Tolerance is  $\pm 0.25$  (0.01") unless otherwise noted.
3. Lead spacing is measured where the leads emerge from the package.

### LabelStyle



### Packaging



## Precautions

### 1. Lead Forming

- 1.1 During lead formation, the leads should be bent at a point at least 3mm from the base of the epoxy bulb.
- 1.2 Lead forming should be done before soldering.
- 1.3 Avoid stressing the LED package during leads forming. The stress to the base may damage the LED's characteristics or it may break the LEDs.
- 1.4 Cut the LED lead frames at room temperature. Cutting the lead frames at high temperatures may cause failure of the LEDs.
- 1.5 When mounting the LEDs onto a PCB, the PCB holes must be aligned exactly with the lead position of the LED. If the LEDs are mounted with stress at the leads, it causes deterioration of the epoxy resin and this will degrade the LEDs.

### 2. Storage

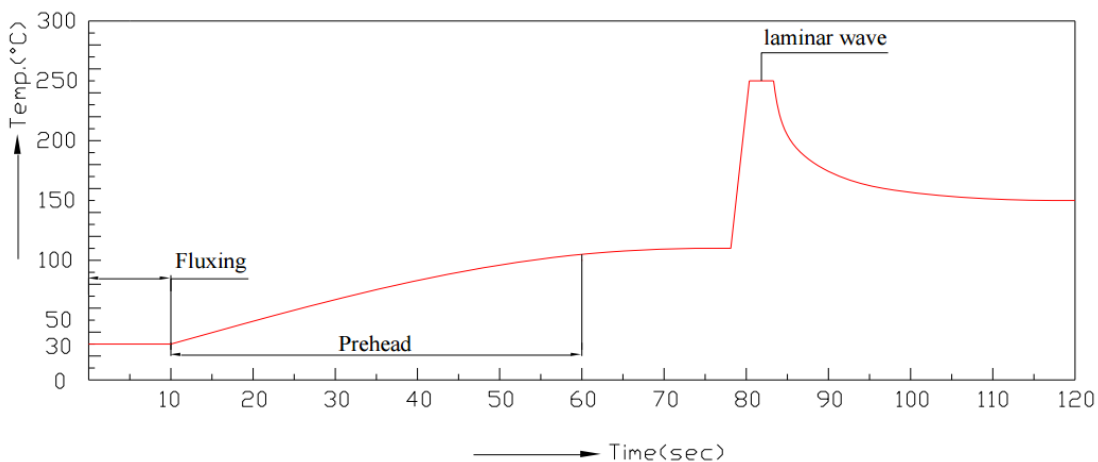
- 2.1 The LEDs should be stored at 30°C or less and 70%RH or less after being shipped and the storage life limits are 3 months. If the LEDs are stored for 3 months or more, they can be stored for a year in a sealed container with a nitrogen atmosphere and moisture absorbent material.
- 2.2 Please avoid rapid transitions in ambient temperature, especially, in high humidity environments where condensation can occur.

### 3. Soldering

- 3.1 Careful attention should be paid during soldering. When soldering, leave more than 3mm from solder joint to epoxy bulb, and soldering beyond the base of the tie bar is recommended.
- 3.2 Recommended soldering conditions:

Hand Soldering		DIP Soldering	
Temp. at tip of iron	300°C Max. (30W Max.)	Preheat temp.	100°C Max. (60 sec Max.)
Soldering time	3 sec Max.	Bath temp. & time	260 Max., 5 sec Max
Distance	3mm Min.(From solder joint to epoxy bulb)	Distance	3mm Min. (From solder joint to epoxy bulb)

### 3.3 Recommended soldering profile



- 3.4 Avoiding applying any stress to the lead frame while the LEDs are at high temperature particularly when soldering.
- 3.5 Dip and hand soldering should not be done more than one time
- 3.6 After soldering the LEDs, the epoxy bulb should be protected from mechanical shock or vibration until the LEDs return to room temperature.
- 3.7 A rapid-rate process is not recommended for cooling the LEDs down from the peak temperature.
- 3.8 Although the recommended soldering conditions are specified in the above table, dip or hand soldering at the lowest possible temperature is desirable for the LEDs.
- 3.9 Wave soldering parameter must be set and maintain according to recommended temperature and dwell time in the solder wave.

**4. Cleaning**

- 4.1 When necessary, cleaning should occur only with isopropyl alcohol at room temperature for a duration of no more than one minute. Dry at room temperature before use.
- 4.2 Do not clean the LEDs by the ultrasonic. When it is absolutely necessary, the influence of ultrasonic cleaning on the LEDs depends on factors such as ultrasonic power and the assembled condition. Ultrasonic cleaning shall be pre-qualified to ensure this will not cause damage to the LED